

12-5-00

**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 2811**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Toshinori NAKAYAMA

Application No.: 09/626,146

Filed: July 26, 2000

For: SUBSTRATE FOR SEMICONDUCTOR DEVICE, SEMICONDUCTOR CHIP  
MOUNTING SUBSTRATE, SEMICONDUCTOR DEVICE AND METHOD OF  
FABRICATION THEREOF, AND CIRCUIT BOARD, TOGETHER WITH  
ELECTRONIC EQUIPMENT

Group Art Unit: 2811

Examiner: O. Nadav

Docket No.: 106364

TECHNOLOGY CENTER 2800

#14  
Req Ext  
Am. 11-15-02  
F. Jones  
11-15-02  
D

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the Office Action dated April 23, 2002, please amend the above-identified  
application as follows:

**IN THE CLAIMS:**

Please replace claim 17 as follows:

B1 SUB C1 17. (Twice Amended) The semiconductor device as defined in claim 15,  
10/25/2002 CHOLLISH 00000003 09626146  
01 FC:1253 wherein the indented portion of the substrate is a surface of a thinner portion  
of the substrate.